

WAFER LEVEL PACKAGE FOR MICRO DEVICE AND MANUFACTURING METHOD
THEREOF

Inventor: Joo Ho LEE

Docket No. 2336-248

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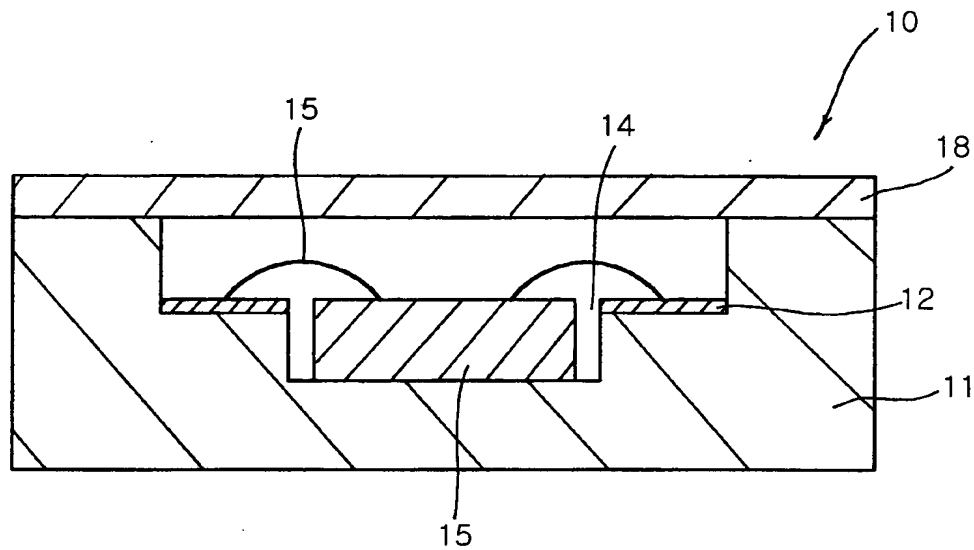


FIG. 1
PRIOR ART

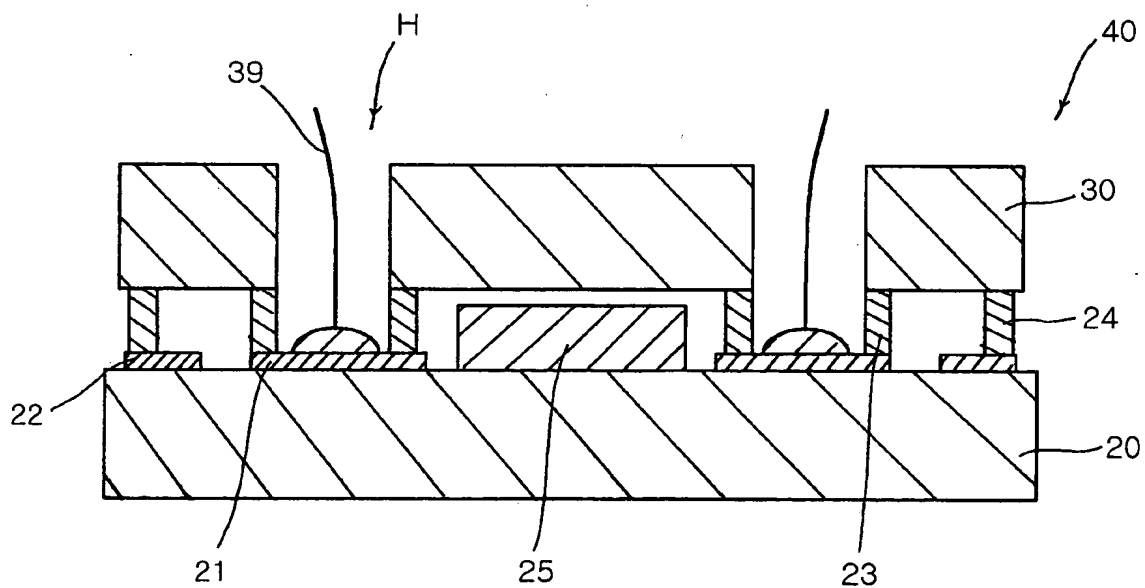


FIG. 2
PRIOR ART

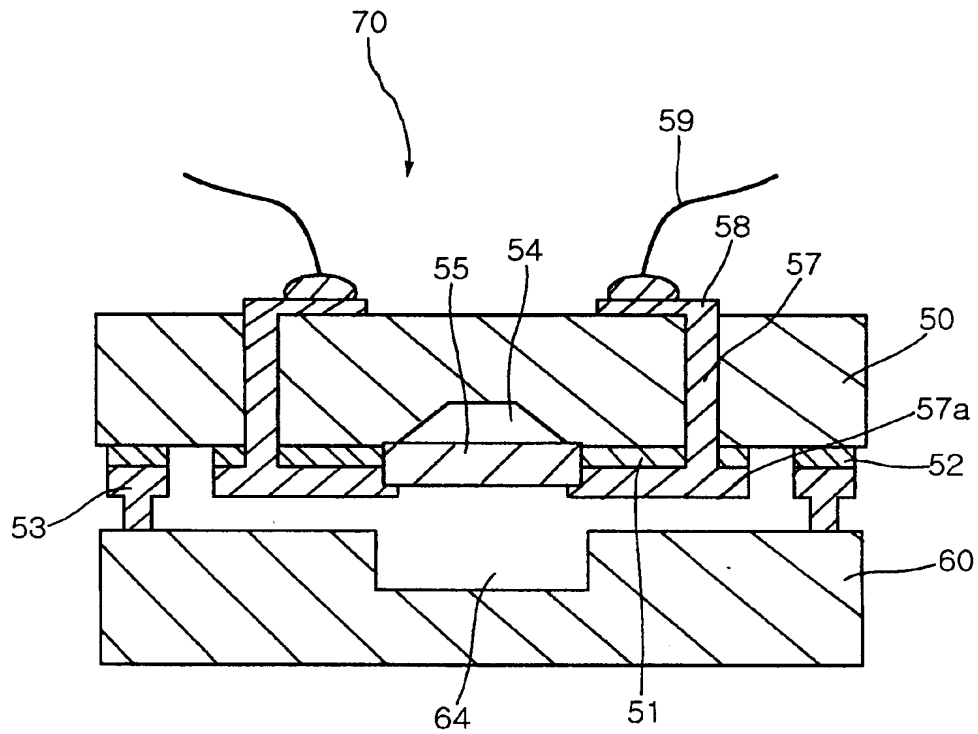
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(a)



(b)

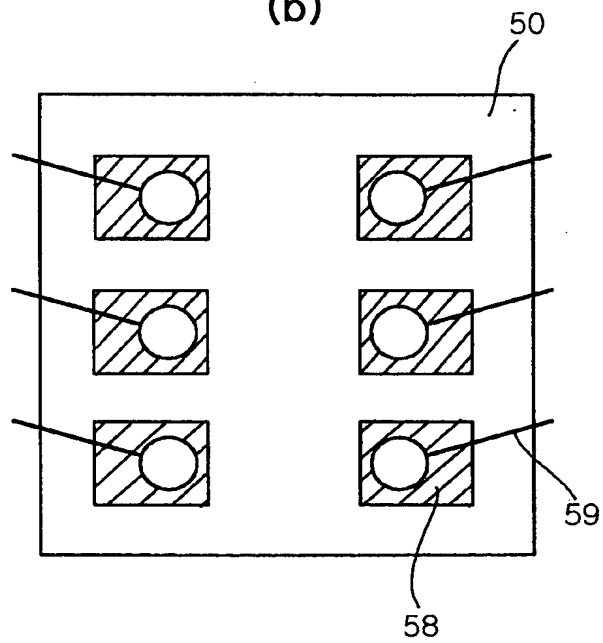


FIG. 3

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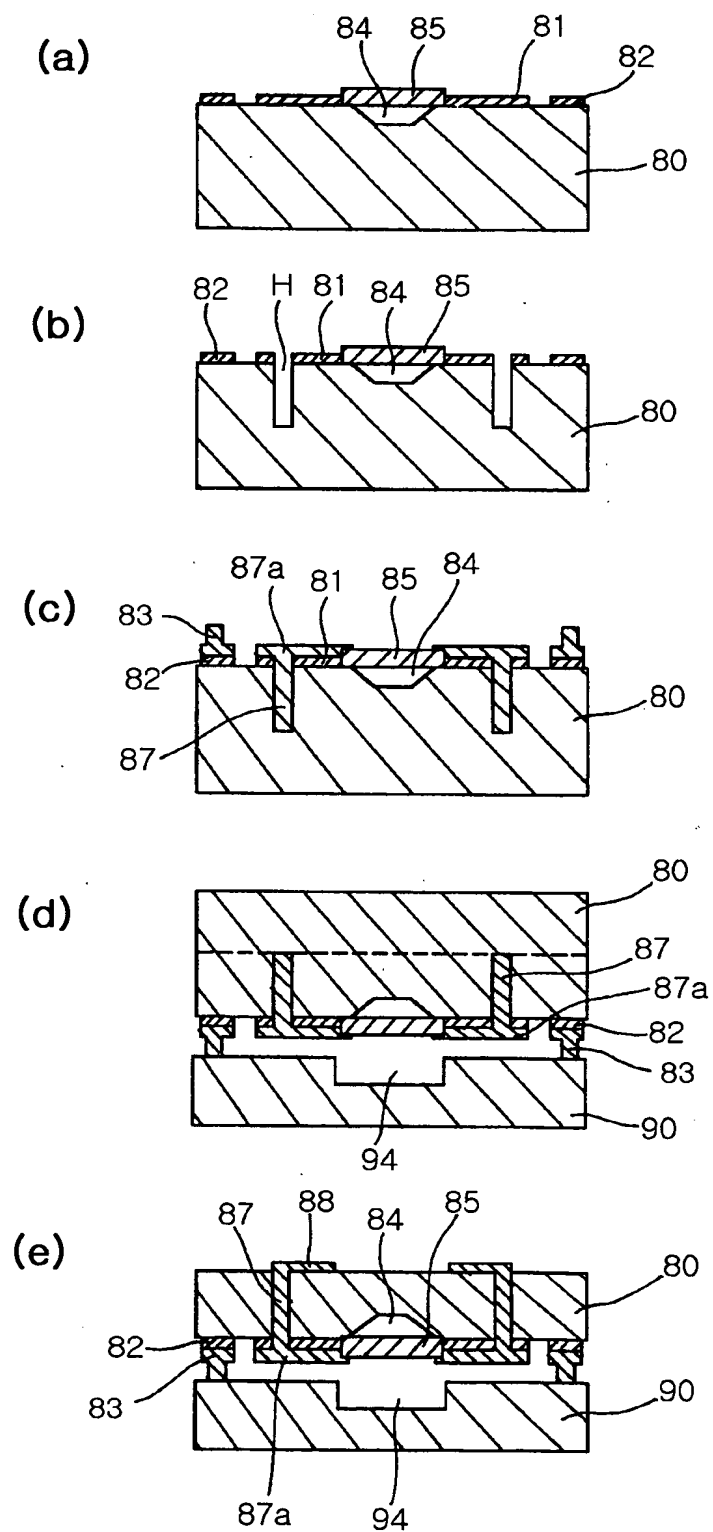


FIG. 4

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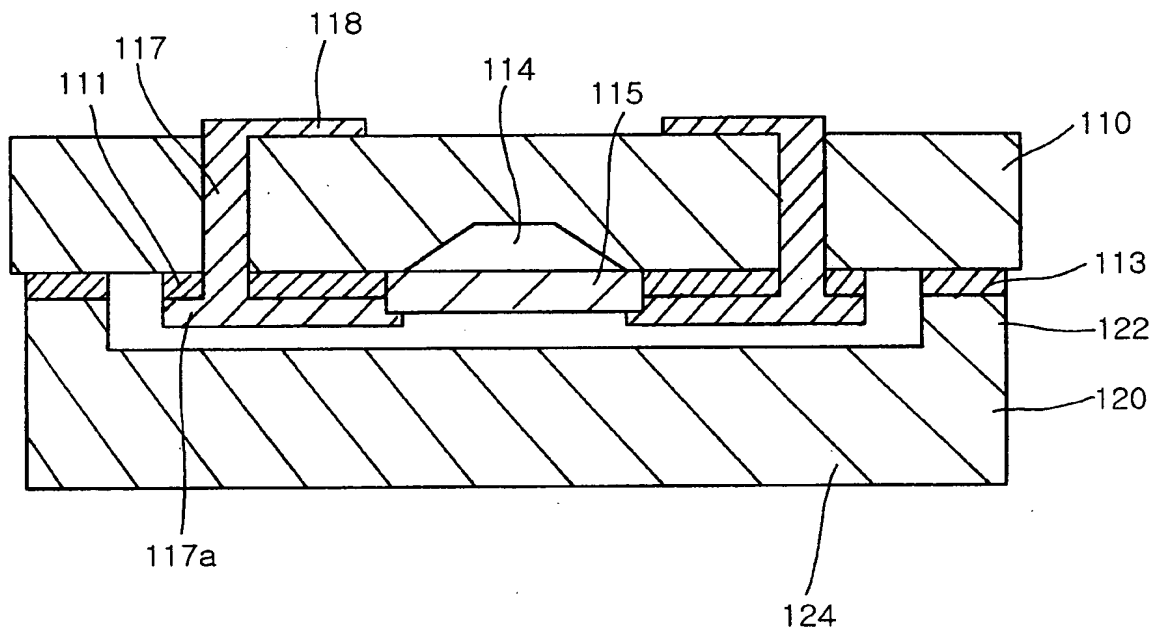


FIG. 5

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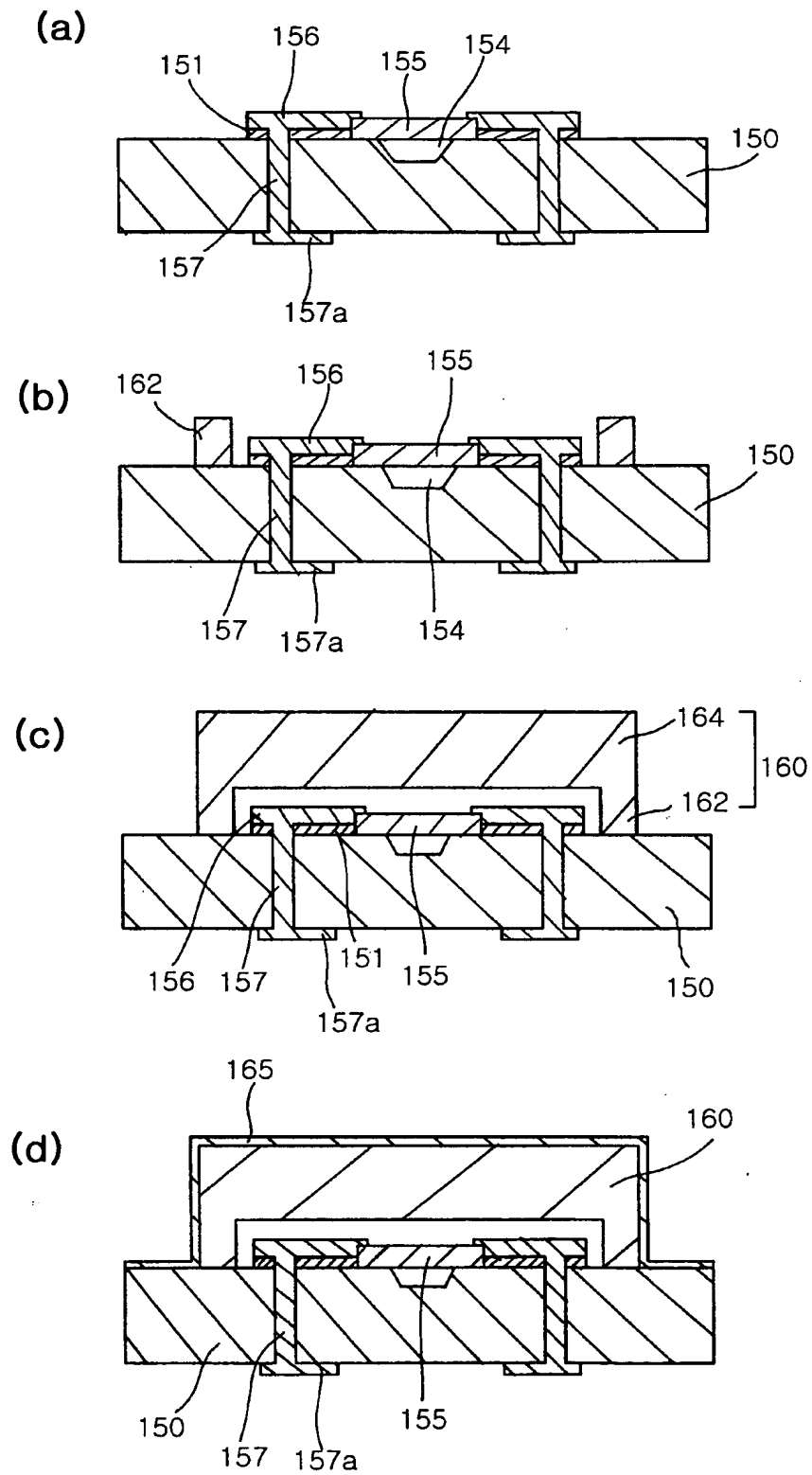


FIG. 6